

Features

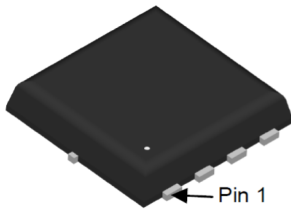
- Low FOM $R_{DS(on)} \times Q_{gd}$
- 100% avalanche tested
- Easy to use/drive
- RoHS compliant

Application

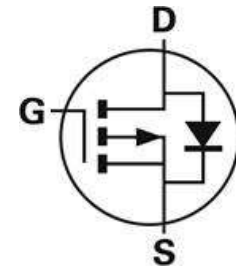
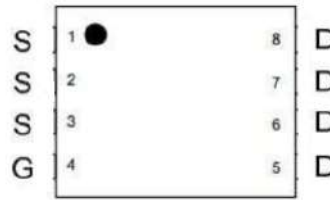
- Power Switch Circuit of Adaptor and Charger
- Battery Protection Charge/Discharge
- Notebook AC-in Load Switch

Product Summary


V_{DS}	-30	V
$R_{DS(on),TYP} @ V_{GS}=10\text{ V}$	6.4	m Ω
I_D	-55	A



PDFN3*3-8


Maximum Ratings $T_A = 25^\circ\text{C}$, unless otherwise noted

	Symbol	Values	Unit
-Source voltage ($V_{GS}=0\text{V}$)	V_{DS}	-30	V
Drain Current ²⁾	I_D	$c = 25^\circ\text{C}$	-55
		$c = 100^\circ\text{C}$	-34.6
Drain Current ³⁾	$I_{D,pulse}$	-220	A
-Source Voltage	V_{GSS}	± 25	V
	E_{AS}	200	mJ
Dissipation	P_D	31.2	W
Junction and Storage Temperature Range	T_J, T_{stg}	-55~+150	$^\circ\text{C}$

Parameter	Symbol	Max.	Unit
Thermal Resistance, Junction-to-Case	R_{thJC}	4	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	R_{thJA}	35	$^\circ\text{C/W}$

Notes

- 1) $L=0.5\text{mH}, V_{DD}=-15\text{V}, \text{Start } T_J=25^\circ\text{C}$
- 2) Limited by maximum junction temperature.
- 3) Repetitive Rating: Pulse width limited by maximum junction temperature.

Electrical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -30V$ $V_{GS} = 0V, T_J = 25^\circ\text{C}$	--	--	-1	μA
		$V_{DS} = -24V$, $V_{GS} = 0V, T_J = 125^\circ\text{C}$	--	--	-100	
Gate-Source Leakage Current	I_{GSS}	$V_{GS} = \pm 25V$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1.2	-1.8	-2.5	V
Drain-Source On-State-Resistance	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -20A$	--	6.4	8	$m\Omega$
		$V_{GS} = -4.5V, I_D = -10A$	--	10.5	13	$m\Omega$
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{GS} = 0V$, $V_{DS} = -15V$ $f = 1.0\text{MHz}$	--	3482	--	μF
Output Capacitance	C_{oss}		--	400	--	
Reverse Transfer Capacitance	C_{rss}		--	309	--	
Total Gate Charge	Q_g	$V_{DS} = -15V, I_D = -10A$ $V_{GS} = -10V$	--	61	--	nC
Gate-Source Charge	Q_{gs}		--	12	--	
Gate-Drain Charge	Q_{gd}		--	10	--	
Gate Plateau Voltage	$V_{plateau}$		--	3.1	--	V
Turn-on Delay Time	$t_{d(on)}$	$V_{DS} = -15V, V_{GS} = -10V$ $R_G = 3\Omega, I_D = -10A$	--	19	--	ns
Turn-on Rise Time	t_r		--	33	--	
Turn-off Delay Time	$t_{d(off)}$		--	38	--	
Turn-off Fall Time	t_f		--	15	--	
Drain-Source Body Diode Characteristics						
Body Diode Forward Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{SD} = -10A$, $V_{GS} = 0V$	--	--	-1.2	V
Continuous Diode Forward Current	I_S		--	--	-55	A
Reverse Recovery Time	t_{rr}	$I_F = -10A, di_F/dt = -100A/\mu s$	--	45	--	ns
Reverse Recovery Charge	Q_{rr}		--	29	--	nC

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

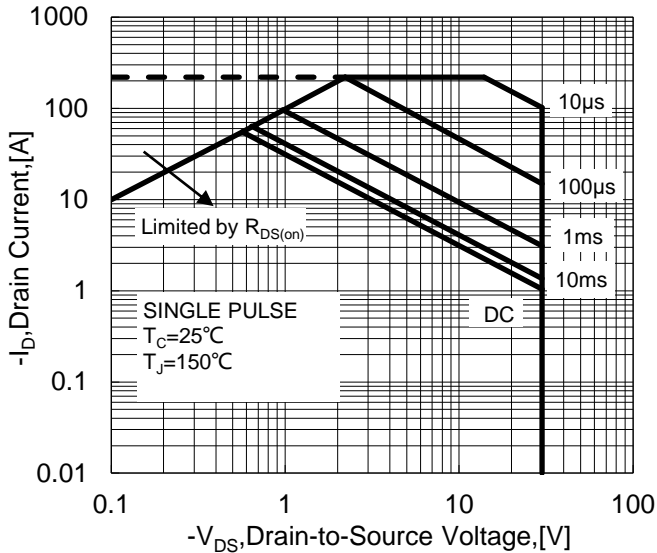


Figure 1. Maximum Safe Operating Area

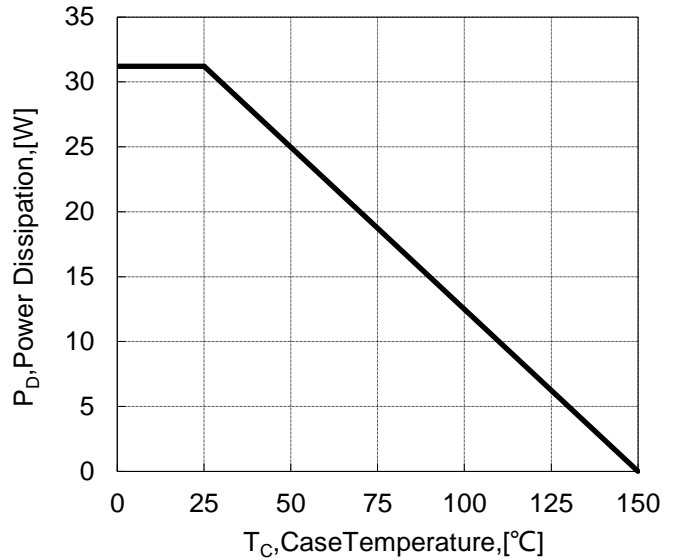


Figure 2. Maximum Power Dissipation vs Case Temperature

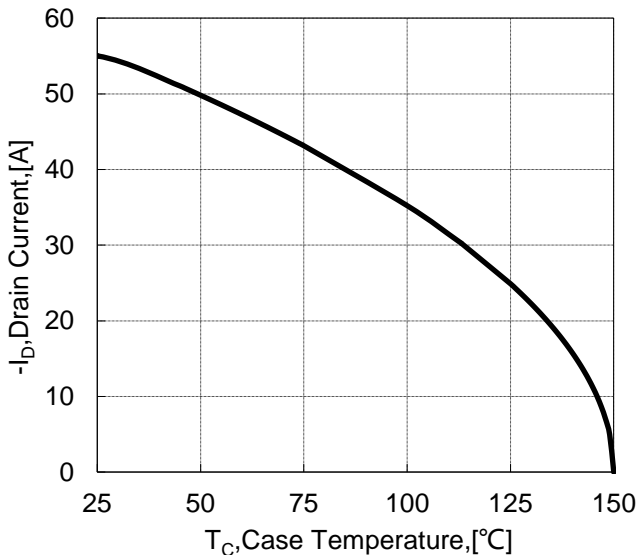


Figure 3. Maximum Continuous Drain Current vs Case Temperature

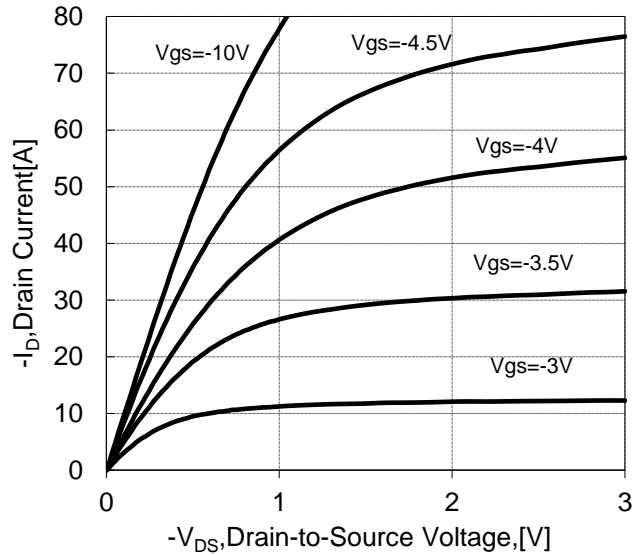


Figure 4. Typical output Characteristics

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

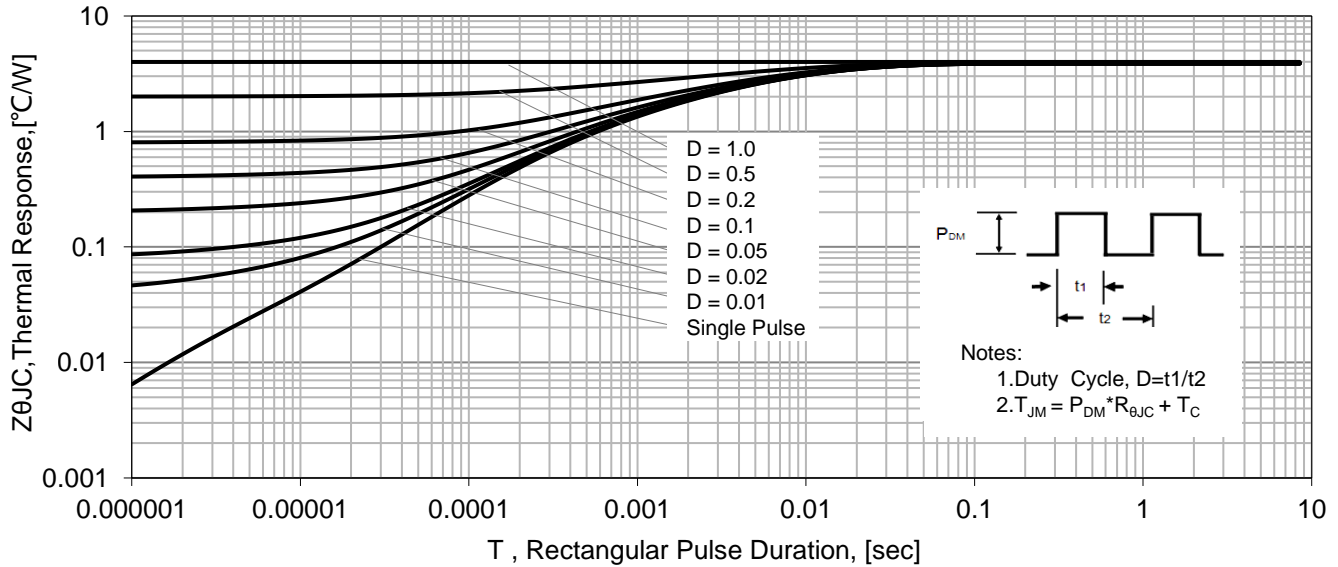


Figure 5 Maximum Effective Thermal Impedance , Junction to Case

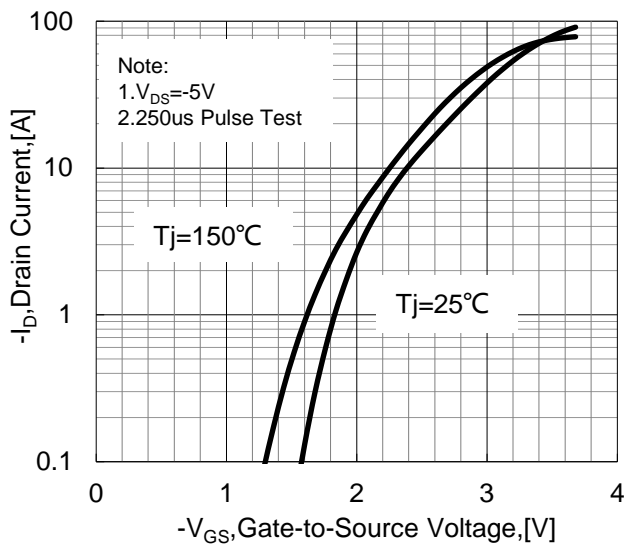


Figure 6 Typical Transfer Characteristics

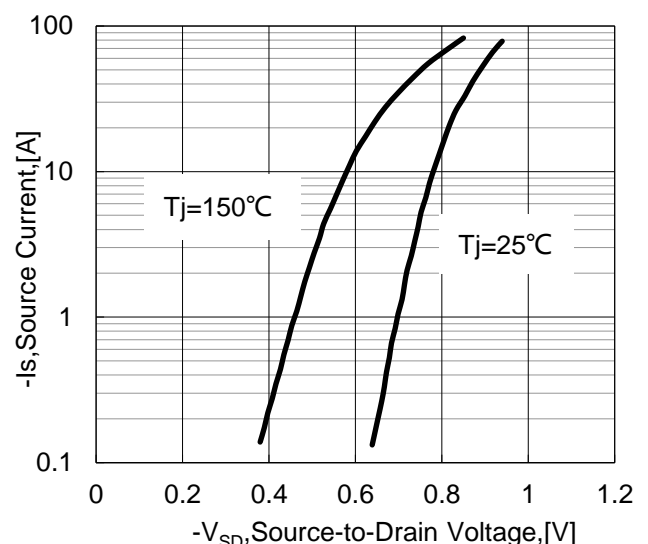


Figure 7 Typical Body Diode Transfer Characteristics

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

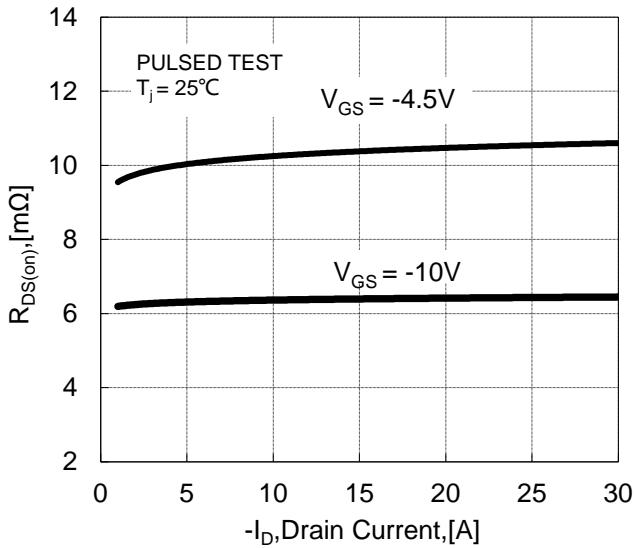


Figure 8. Drain-to-Source On Resistance vs Drain Current

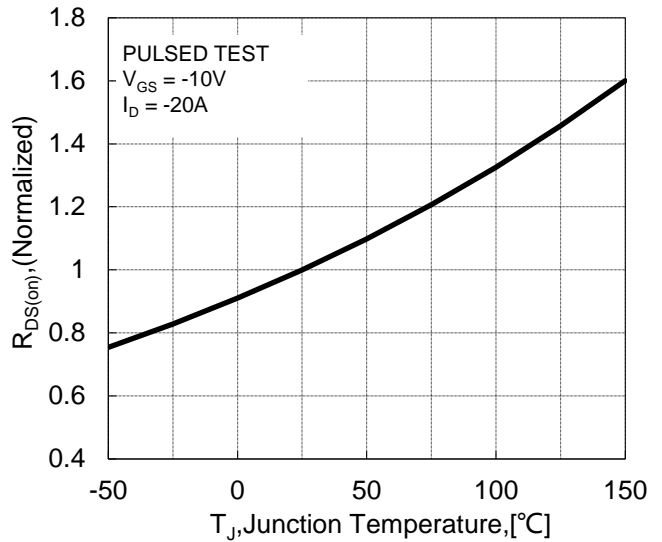


Figure 9. Normalized On Resistance vs Junction Temperature

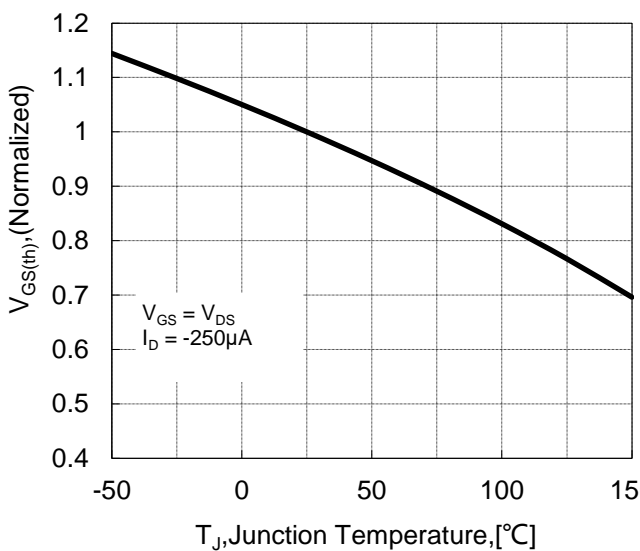


Figure 10. Normalized Threshold Voltage vs Junction Temperature

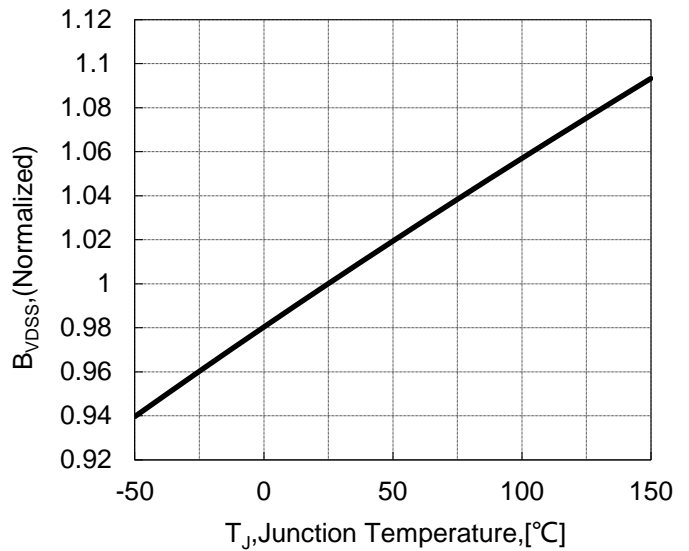


Figure 11. Normalized Breakdown Voltage vs Junction Temperature

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

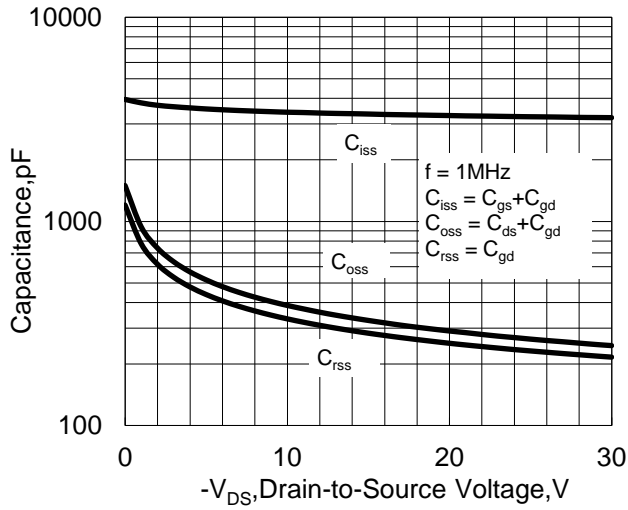


Figure 12. Capacitance Characteristics

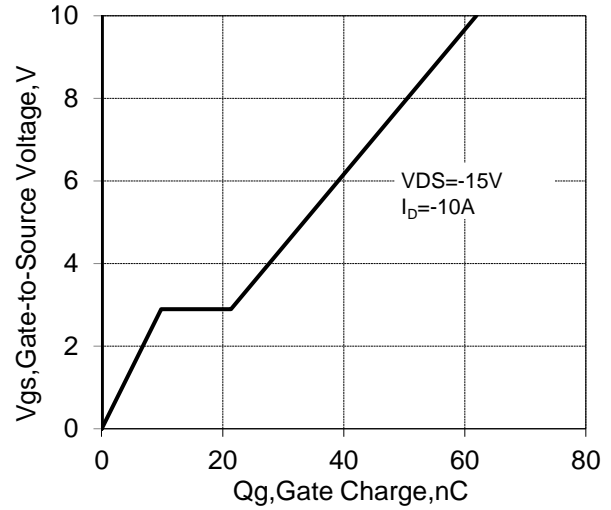
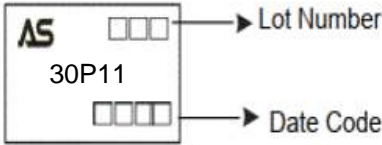


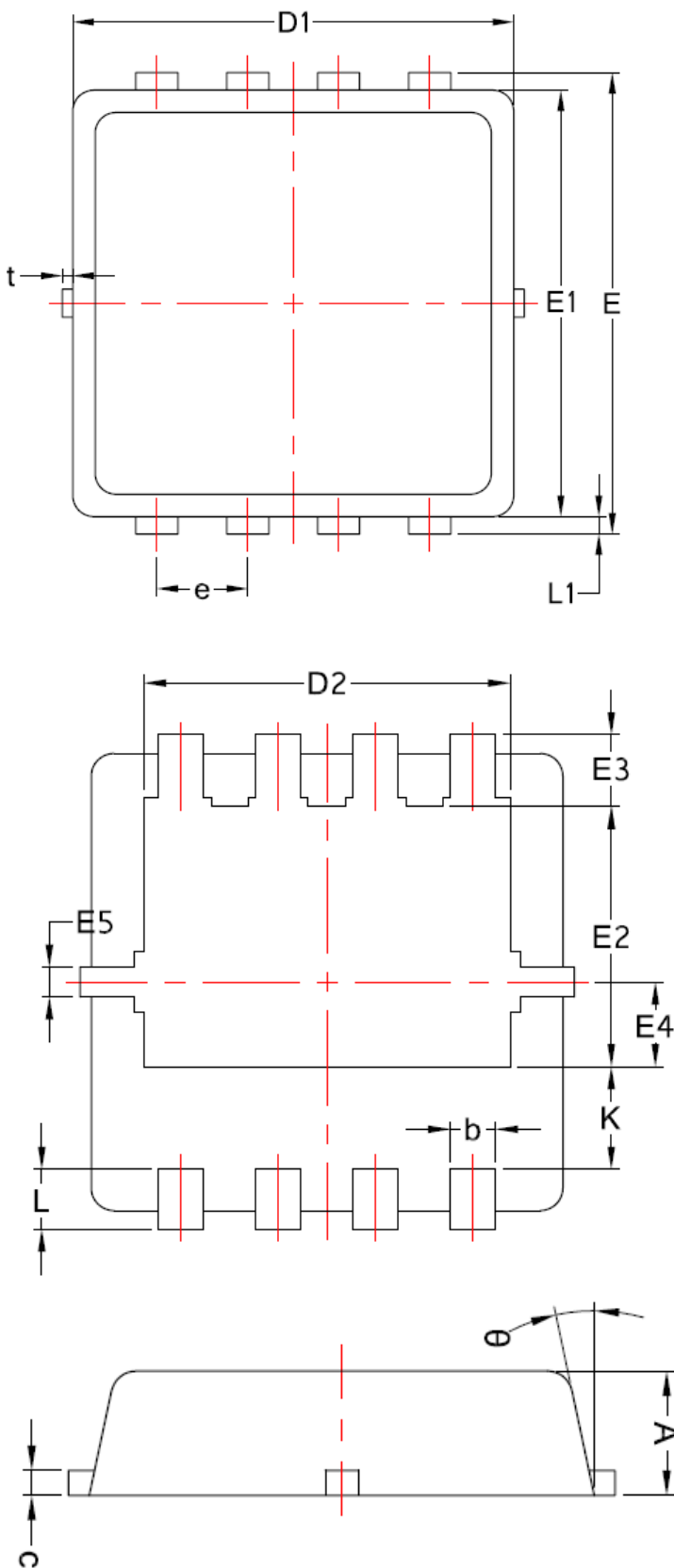
Figure 13 Typical Gate Charge vs Gate to Source Voltage

Ordering and Marking Information

Ordering Device No.	Marking	Package	Packing	Quantity
ASDM30P11TD-R	30P11	PDFN3*3-8	Tape&Reel	5000/Reel

PACKAGE	MARKING
PDFN3*3-8	 <p>AS □□□ → Lot Number 30P11 □□□□ → Date Code</p>

PDFN3*3_8 Package



SYMBOL	COMMON		
	MM		
	MIN	NOM	MAX
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
θ	10°	12°	14°

IMPORTANT NOTICE

ShenZhen Ascend Semiconductor incorporated MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

ShenZhen Ascend Semiconductor Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. ShenZhen Ascend Semiconductor Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does ShenZhen Ascend Semiconductor Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume .

all risks of such use and will agree to hold Ascendsemi Incorporated and all the companies whose products are represented on ShenZhen Ascend Semiconductor Incorporated website, harmless against all damages.

ShenZhen Ascend Semiconductor Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use ShenZhen Ascend Semiconductor Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold ShenZhen Ascend Semiconductor Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

www.ascendsemi.com